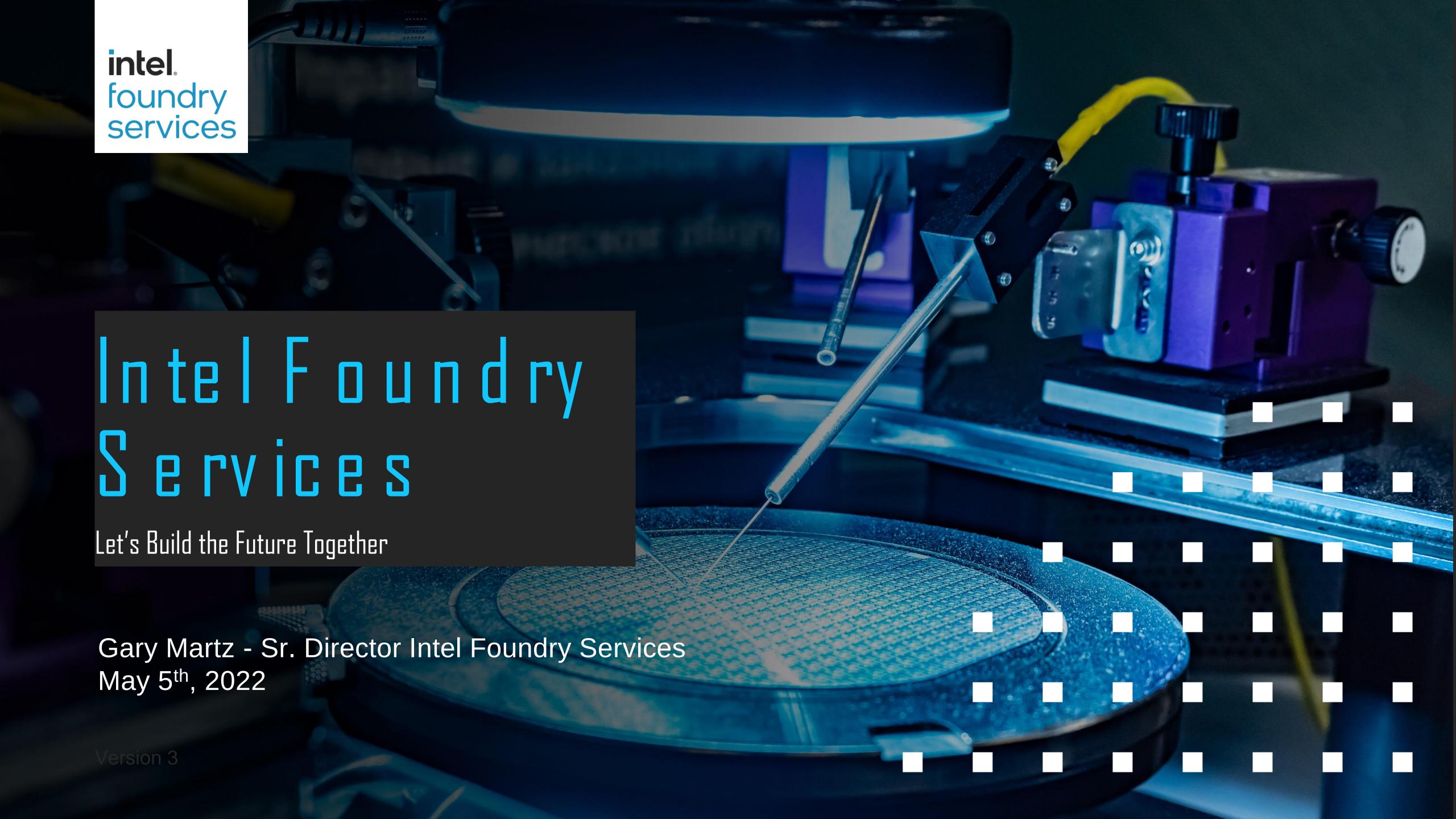
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Innovative Foundry with Global Scale

We will offer a **broad**portfolio to the market ...

O.5um to leading edge silicon technology and advanced 3D Packaging

Multi-ISA support X86 | Arm | RISC-V Robust IP ecosystem Intel + 3rd party

Industry leading innovations: Chiplet Open Platform, LIDAR

... with a customercentric business model ...

Relentless focus on customer service and co-development

Flexible commercial models tailored to customer needs

Industry-focused technology platforms
Auto | Mobile | Compute

\$1B IFS Innovation fund in partnership with Intel Capital

... accelerated by the power of Intel®

Deep technology & manufacturing expertise

Robust supply chain at scale

Only US-based foundry with leading-edge R&D

Globally diverse manufacturing footprint



Intel Foundry Services – Complete Solutions

Intel differentiators available through IFS

World-class foundry offering leveraging the eco-system

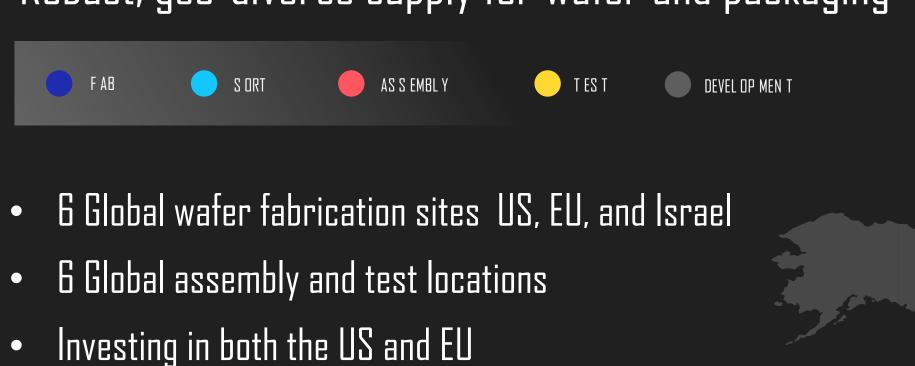
Secure supply

Any Intel Core or Accelerator	X86, AI, Graphics
Any Intel Packaging	EMIB, Foveros, FCBGA with differentiated assembly & test capability
Design Services	Industry-leading Architects, Designers
Any Eco-system Core	Arm, RIS C-V, x86
OSAT network	Use industry OS ATs to package IF S wafers, if you choose
Broad Eco-system IP Offering	IP from leading industry IP providers
Design Enablement	Industry standard PDKs Broad EDA & cloud tool enablement
Manufacturing	Only foundry with R&D in the West and robust, geo-diverse manufacturing



Worldwide Factory Network

Robust, geo-diverse supply for wafer and packaging

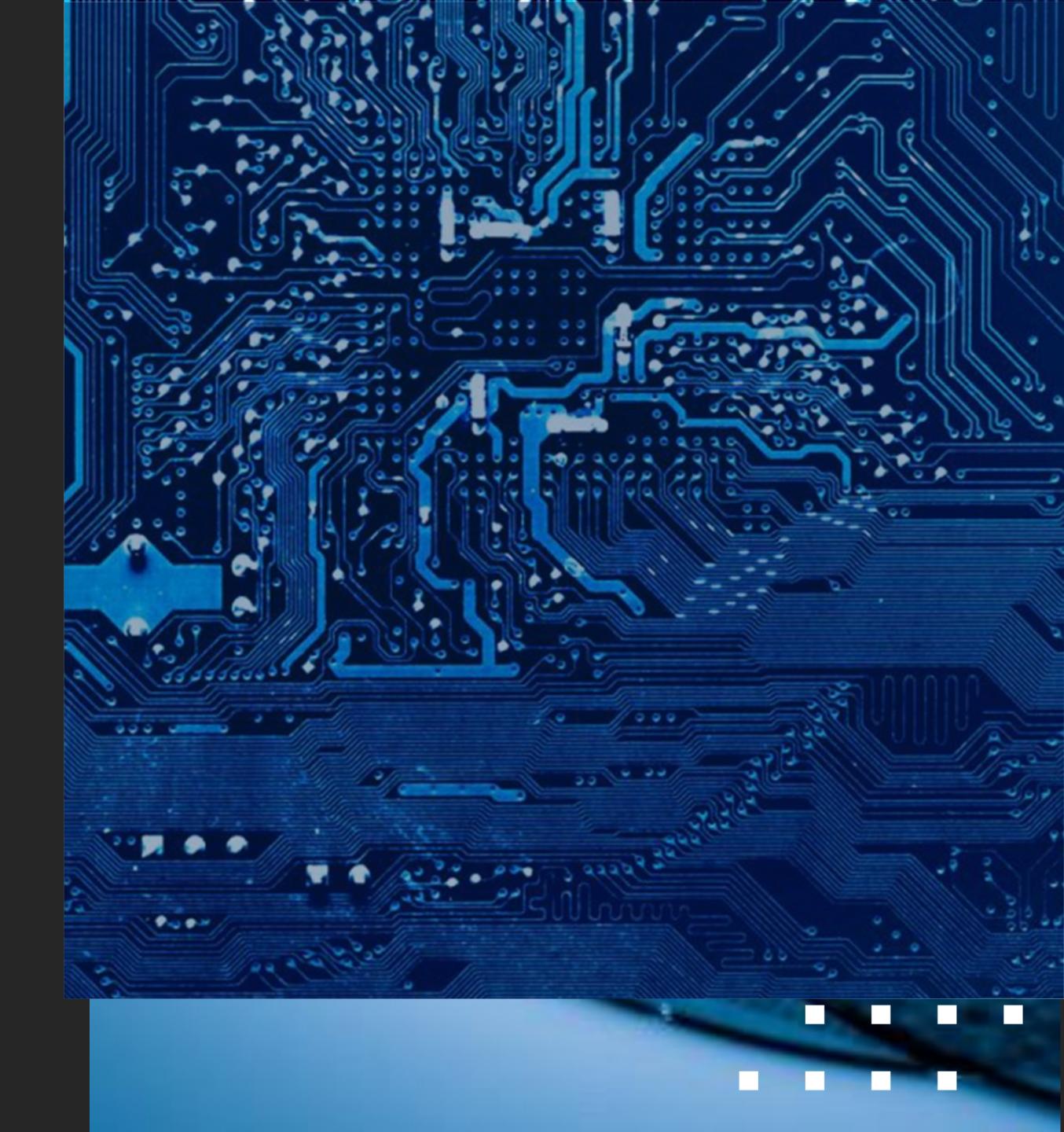


- \$20B for new manufacturing in Ohio
- \$20B for new manufacturing in Arizona
- \$3.5B for advanced packaging in New Mexico
- As much as 80 billion euros in the EU over the next decade
 - Manufacturing and foundry services in Ireland, Italy, Poland and Spain
 - 17B Euro for new manufacturing in Germany
 - 12B Euros for Ireland fab expansion
 - New R&D and design hub in France





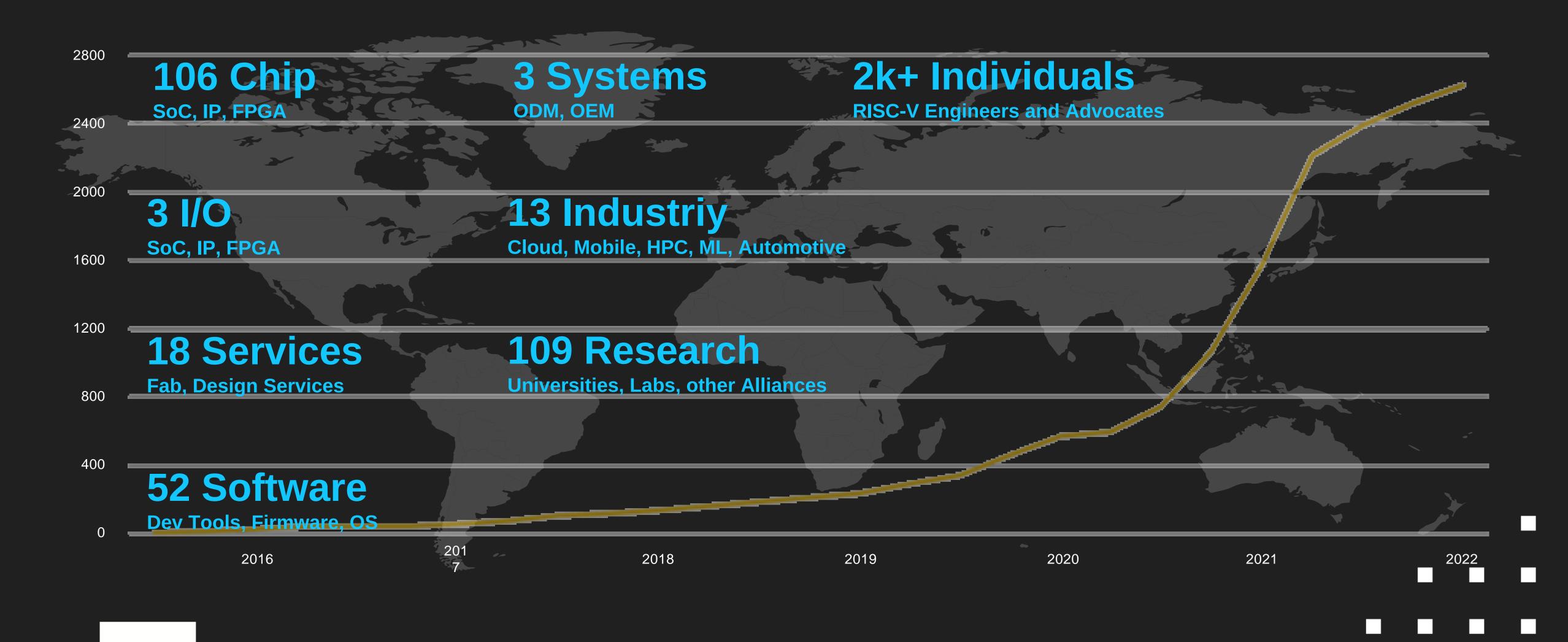
RISC-V Growth



Currently 2,700+ RISC-V Members

intel.

foundry services



Source: RISC-V International

RISC-V Future

Semico Research has estimated that

Demand will continue to grow at a rapid pace,

with the market consuming

more than 60 billion RISC-V CPU cores by 2025



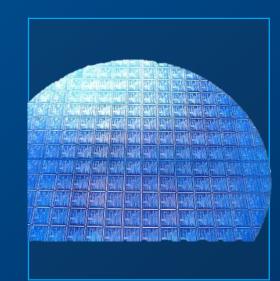
Intel Foundry Services \$18 Innovation Fund

- Equity investments in disruptive start-ups
- Strategic investments for scale partnerships
- Ecosystem investments for IFS scale

IP, Architecture, Tools & Software



Priority Wafer Shuttles



Multi ISA Ecosystem

intel® x86
arm

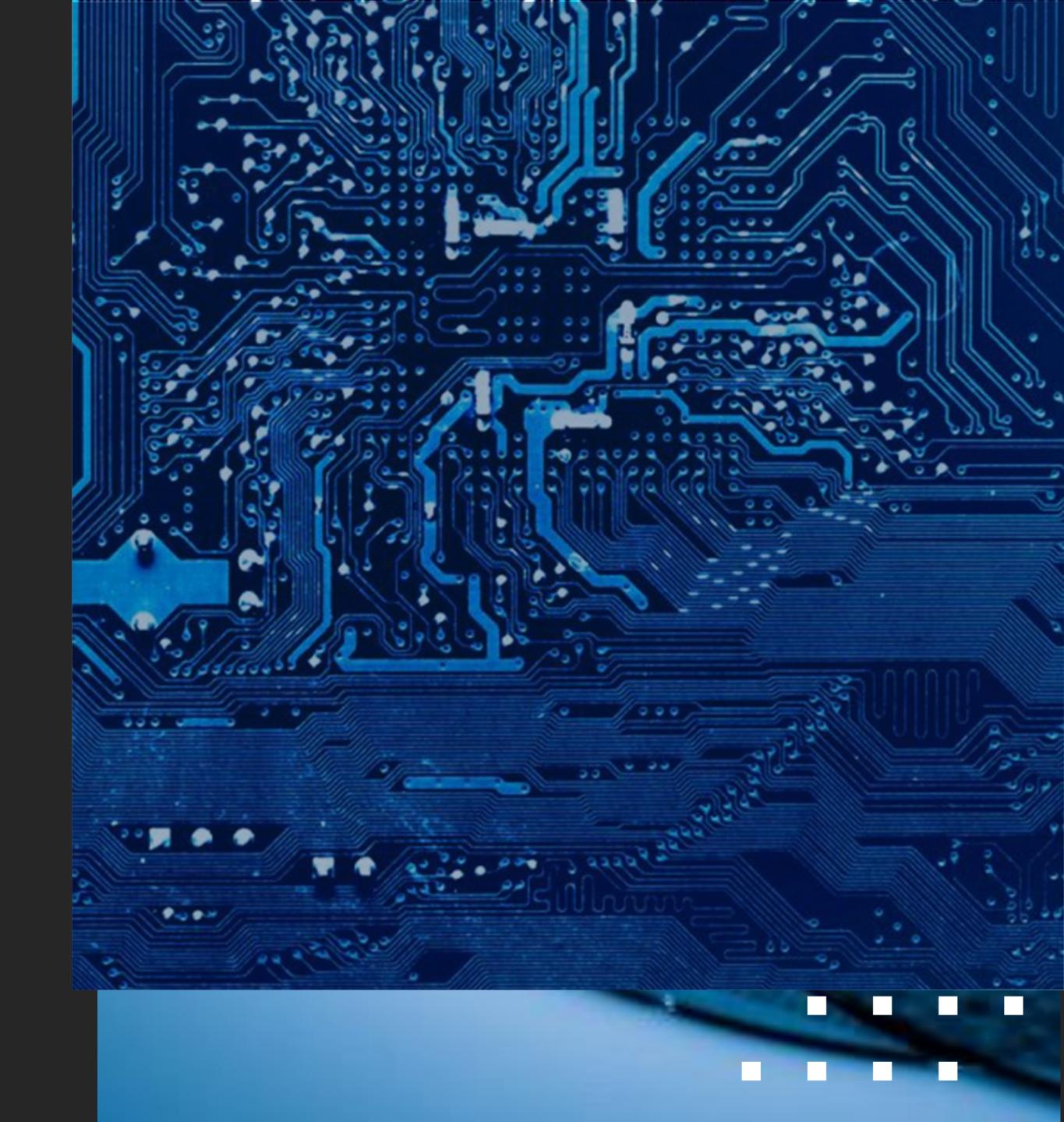
SiFive VENTANA — esperanto.ai ANDES MICRO

Target applications

- Next-gen leaders of semiconductors (AI/ML/DL, Auto)
- IP Providers
- RISC-V ecosystem
- Semiconductor Devices
- Semiconductor Tools/EDA
- Semiconductor manufacturing Equipment/Materials
- Chiplet ecosystem / Next-gen packaging



Working Together



Enabling the growth of the RISC-V Ecosystem

SoC Architecture

Boot, Security, and FW resilience

Isolation/Partioning

Power and Thermal Management

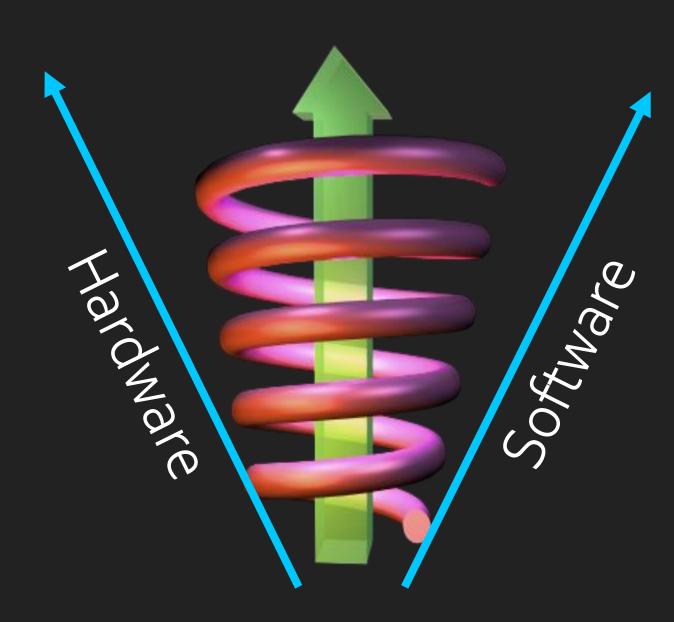
Virtualization

Confidential Computing

Reliability, Availability, Serviceability

Performance monitoring, telemetry, debug and trace

Semiconductor Growth



Strategic Collaboration \$1B Innovation Fund

Open Software

Applications

Operating System

Virtualization

BIOS

Firmware

Tools & Compilers



Enabling the growth of the RISC-V Ecosystem

SoC Architecture

Boot, Security, and FW resilience

Isolation/ Partioning

Power and Thermal Management

Virtualization

Confidential Computing

Reliability, Availability, Serviceability

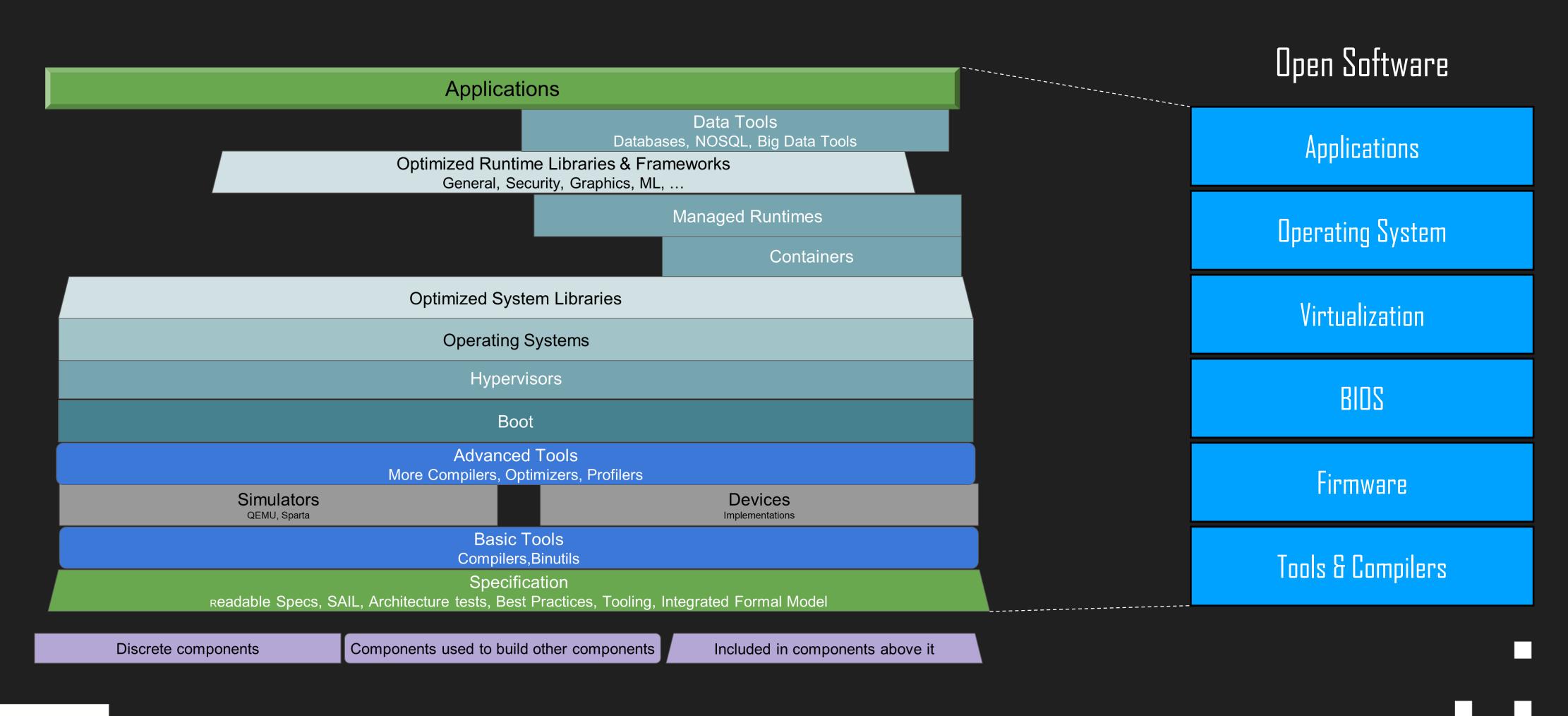
Performance monitoring, telemetry, debug and trace

HW Innovation

- Robust E2E secure solutions
- Minimize fragmentation
- Standard internal buses for various bus types
- Fabrics infrastructure for multi-core architecture and coherency for low power to high-performance markets
- Holistic debug solutions and interfaces to cover hardware and software requirements
- Optimize segment specific SoC architecture, e.g. Datacenter RAS, Security, Automotive ASIL-B/D, Mobile Power Management



Enabling the growth of the RISC-V Ecosystem

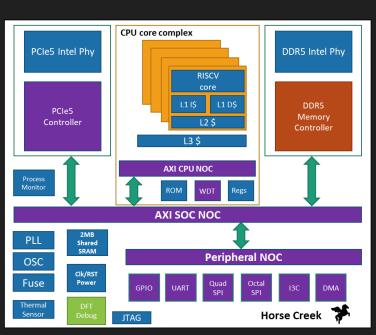




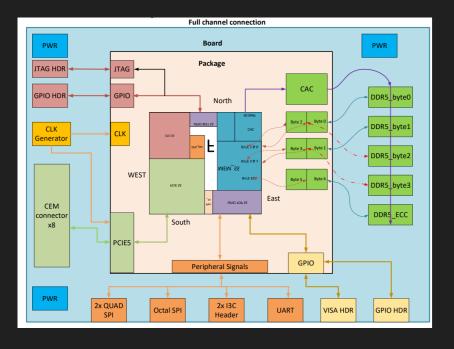
IFS RISC-V Ecosystem Enablement

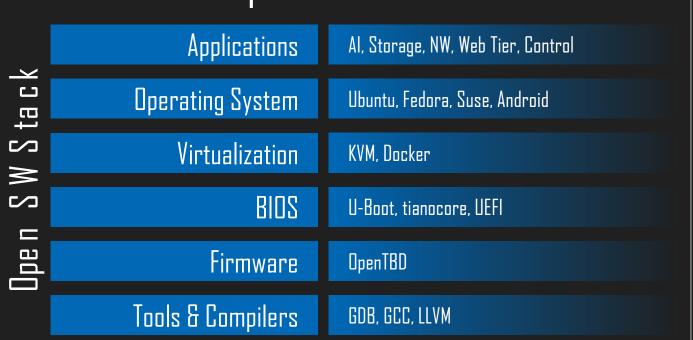
Grow RISC-V Ecosystem





Horse Creek Boards : Software Development Vehicles





IFS Partners

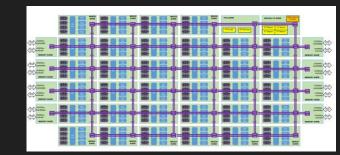


Highest Performance



Scale up RISC-V AI





Embedded Core







Thankyou

